TDCpix - Pixel Read-out ASIC with 100 ps Time-tagging Capability for the NA62 Gigatracker Experiment

 $\label{eq:main_state} \underbrace{ \begin{array}{ccc} \underline{\mathsf{M}}. \ \mathsf{Noy}^a & \mathsf{G}. \ \mathsf{Aglieri} \ \mathsf{Rinella}^a & \mathsf{S}. \ \mathsf{Bonacini}^a & \mathsf{J}. \ \mathsf{Kaplon}^a & \mathsf{A}. \ \mathsf{Kluge}^a \\ & \mathsf{M}. \ \mathsf{Morel}^a & \mathsf{L}. \ \mathsf{Perktold}^a & \mathsf{K}. \ \mathsf{Poltorak}^a \end{array} }$

^aCERN, CH-1211 Geneva 23, Switzerland

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Introduction to NA62 and the GigaTracker

The TDCPix Chip Architecture

Measured Performance

Pixel Jitter: Test Output TDC Performance Full Chain Performance

Summary

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Summary

The NA62 Experiment



Trajectory

- momentum
- angle

Time

- correlate hits with RICH
- $\leq 200 \, ps(RMS)$ per station

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Introduction to NA62 and the GigaTracker

GTK Station in the Beam Line



▶ in vacuum ▶ centred on the beam ▶ $0.8 \rightarrow 1 \text{ GHz}$ beam rate

Introduction to NA62 and the GigaTracker



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7000 6000 4000 2000 00 2 4 6 8 10 12 14 16 18 20 Charge [C] Charge [C]

- Planar P-on-N
- ▶ Thickness: 200µm
- $V_{bias} \sim$ 300-600V
- charge release mechanism is stochastic
- Landau distribution
 - $Q_{MP} = 2.4 fC$
 - ▶ $1 fC \le Q \le 10 fC$
- Segmented electrodes give spatial information

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Pre-Amplifier & Discriminator Signals





matthew.noy@cern.ch

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Pre-Amplifier & Discriminator Signals



matthew.noy@cern.ch

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Summary

- 40 x 45 pixels
 - ▶ 300x300 µm²
 - asynchronous



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 - per-pixel hit signal to EOC



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 - Rate:210MHits/s
 - ▶ 4 x 3.2 Gb/s serialisers



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 - Rate:210MHits/s
 - ▶ 4 × 3.2 *Gb/s* serialisers
- SEE Tolerant
 - state/config.







The TDCPix Chip Architecture





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Simplified Pixel Architecture



- Gain $\sim 65 \, mV/fC$
- peaking time $\sim 5\,ns$
- ▶ ENC < $250 e^-$

- Polarity control
- Pixel mask
- TX with pre-emphasis

ъ.

Pixel Layout:



$300 \mathrm{x} 300 \mu m^2$ cell

Pixel Layout: Signal Path





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Pixel Layout: Trimming & Configuration

In-Pixel Configuration





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Pixel Layout: Noise Mitigation

Triple Well **BFMOAT** Substrate Isolation Signal Shielding Thick Oxide Caps



- Triple well (input transistor)
- BFMOAT substrate isolation
- signal shielding
- Power supply decoupling



The TDCPix Chip Architecture

FDC: Schematic and Layout

matthew.nov@cern.ch

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The TDCPix Chip Architecture

FDC: Schematic and Layout



The TDCPix Chip Architecture

FDC: Schematic and Layout



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FDC: Schematic and Layout



The TDCPix Chip Architecture

FDC: Schematic and Layout



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TDCPix Wire Bonded to the Test Card



TDCPix Wire Bonded to the Test Card



matthew.noy@cern.ch

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Introduction to NA62 and the GigaTracker

The TDCPix Chip Architecture

Measured Performance Pixel Jitter: Test Output TDC Performance Full Chain Performance

Summary

Functionality Tested

Block	Status	Remarks
Configuration	Working	5 chips tested
PLL	Working	3.2 GHz
Serialisers	Working	3.2 Gb/s
Bandgaps	Working	
Temperature Interlock	Working	
Column Biasing	Working	200 DACs
In-Pixel Threshold Trimming	Working	1800 DACs
# of bugs detected	0	

First Working Silicon

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Full Pixel Array Gain & ENC Distributions





$$\label{eq:Gain} \begin{split} <\mathsf{Gain}\!>&= 62\,\text{mV/fC}\\ \mathsf{Spread} &= 1.1\,\text{mV/fC} \end{split}$$

$$<$$
ENC $> = 170e^{-}$ No sensor

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Pixel Jitter: Test Output



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TDC Performance

TDC Test Input: Code Density Histograms



- 16 million random (unsynchronised) triggers
- bin content gives width estimate

TDC Test Input: Transfer Curves



Bin widths give the transfer curve

TDC Test Input: INL



transfer curves give the INLs

Leading/Trailing INL: All TDC Channels



Distribution of Leading Fine INL

Distribution of Trailing Fine INL

RMS INL \sim 0.15 LSBs

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TDC Performance



- Pixel Matrix not involved in measurement
- ► Two clock periods (2*3.125ns)
- Step: 10 ps
- ► 3.10⁴ triggers/pt.

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TDC Performance



- Pixel Matrix not involved in measurement
- ► Two clock periods (2*3.125ns)
- Step: 10 ps
- ► 3.10⁴ triggers/pt.

- < A

TDC Resolution



Resolution (Mode of the RMS dist.) \sim 58 ps

- clock/pulse generator synchronisation contributes $\sim 30 \, ps \; {\sf RMS}$
- contribution from signal distribution in the chip unknown

matthew.noy@cern.ch

Full Chain Performance



Full Chain Behaviour



T1 Pixel Jitter Summary for 32 phases for column pair 0, pixel 0

- trigger swept through full clk cycle
 - 32 phases
 - Step:100ps
- 10⁴ triggers per phase
- No sensor present

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Full Chain Behaviour



T1 Pixel Jitter Summary for all Pixels

- trigger swept through full clk cycle
 - 32 phases
 - Step:100ps
- 10⁴ triggers per phase
- No sensor present

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TimeWalk-Corrected Time Resolution



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Summary

Summary

- NA62: Ultra Rare Kaon decay measurement
 - huge beam rate \rightarrow massive background reduction
 - GTK Time Tagging <200ps per station

Summary

- ► NA62: Ultra Rare Kaon decay measurement
 - \blacktriangleright huge beam rate \rightarrow massive background reduction
 - ► GTK Time Tagging <200ps per station

TDCPix Architecture

- 1800 pixel End-of-Column chip
- 20mm x 12mm
- self-triggering architecture
- 4 x 3.2Gb/s on-chip serialisers

Summary

- ► NA62: Ultra Rare Kaon decay measurement
 - \blacktriangleright huge beam rate \rightarrow massive background reduction
 - ► GTK Time Tagging <200ps per station
- TDCPix Architecture
 - ▶ 1800 pixel End-of-Column chip
 - 20mm x 12mm
 - self-triggering architecture
 - ▶ 4 × 3.2Gb/s on-chip serialisers
- TDCPix Performance is excellent
 - First working silicon
 - Pixel jitter < 60 ps RMS at 2.5fC</p>
 - TDC gives <60 ps RMS time resolution</p>
 - Full chain works as expected < 65 ps RMS at 2.5fC</p>
 - Time Walk Correction Works as expected
 - $\blacktriangleright\,$ "Whole Chip" Resolution \sim 72 ps RMS

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Thanks for your attention!!

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Backups

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Backup Slides

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Demonstrator

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EoC Chip & Assembly





- What is the limit of the timing resolution attainable?
- Where does this limit come from?

Summary of Results

Transmission Line Uniformity T_1 RMS Jitter: ASIC



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Backups Summary of Results

RMS T_0 Jitter Vs Q: Assembly (@ 300V) + Laser



- Full event time reconstruction done
- EoC activity doesn't feed through to the pixels

- detector bias = 300 V
- \blacktriangleright average case $\sim 75\,ps$ at $2.4\,fC$

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Beam Test: Time Resolution Vs Detector Bias



M. Fiorini

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Time Resolution Limits





- induced current pulse on electrode changes shape
 - pre-amp output changes shape
 - ► adds ~85ps

G. Aglieri Rinella

Time Resolution Limits





- induced current pulse on electrode changes shape
 - pre-amp output changes shape
 - ► adds ~85ps
- Charge straggling also contributes
 - inhomogeneities in charge deposition
 - adds > 60ps

G. Aglieri Rinella

Time Resolution Limits





- induced current pulse on electrode changes shape
 - pre-amp output changes shape
 - ► adds ~85ps
- Charge straggling also contributes
 - inhomogeneities in charge deposition
 - adds > 60ps
- uncorrectable contributions for current sensor

G. Aglieri Rinella

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Hit Arbiter

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DLL & Hit Registers

TDC: DLL & Fine Registers





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PLL & Serialisers

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Serial Outputs at 3.2Gb/s



- Idle words correct
 - synchronisation works

- ► Total Jitter < 150 ps
- ▶ FPGA GTX recv. lock reliably

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DAQ works reliably

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Pixel Behaviour

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S-Curves \rightarrow Pre-Amp Transfer Function



- Q_{injected} adjusted for CAL DAC gain
- \blacktriangleright Transfer fit \rightarrow discriminator offset and front end gain
- Polarity setup for a hole signal
 - P-on-N sensor (baseline)
 - "electron" polarity works too

Trim and TRANGE Functionality











How low will the threshold go?



- All pixels enabled (& trimmed)
- Pink: minimum threshold $\sim 0.26 fC$ (1600e⁻)
- Blue: nomimal threshold 0.7 fC

Top Level Test Bench



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